



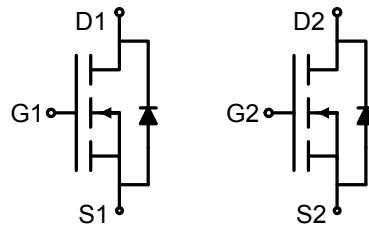
SHENZHEN TUOFENG SEMICONDUCTOR TECHNOLOGY CO.,LTD

N-CHANNEL ENHANCEMENT MODE POWER MOSFET

TFD085N03M

Description

The TFD085N03M uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other switching application.



Schematic diagram

General Feature $V_{DS} = 30V$, $I_D = 25A$ $R_{DS(ON)} \text{ Typ } = 8.5m\Omega$ @ $V_{GS}=10V$ $R_{DS(ON)} \text{ Typ } = 10m\Omega$ @ $V_{GS}=4.5V$

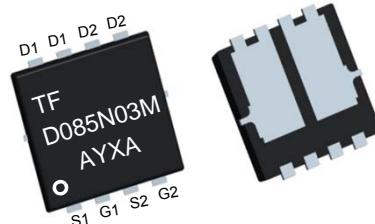
High Power and current handing capability Lead free product is acquired

Surface mount package

Application

Battery switch

DC/DC converter



PDFN3333-8

•Package Marking and Ordering Information:

Part NO.	TFD085N03M
Marking1	D085N03M: TFD085N03M
Marking2	TF:tuofeng; Y:year code; X:Week; AA:device code;
Basic ordering unit (pcs)	5000

•Absolute Maximum Ratings ($T_C = 25^\circ C$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D @ T_C = 25^\circ C$	25	A
	$I_D @ T_C = 75^\circ C$	17	A
	$I_D @ T_C = 100^\circ C$	12	A
Pulsed Drain Current ^①	I_{DM}	75	A
Total Power Dissipation	$P_D @ T_C = 25^\circ C$	16	W
Total Power Dissipation	$P_D @ T_A = 25^\circ C$	0.9	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ C$
Storage Temperature	T_{STG}	-55 to 150	$^\circ C$
Single Pulse Avalanche Energy	E_{AS}	56	mJ



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TFD085N03M

• Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}	-	-	8.0	° C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	55	° C/W
Soldering temperature, wavesoldering for 8 s	T _{sold}	-	-	265	° C

• Electronic Characteristics(T_j=25 °C, unless otherwise note)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D = 250uA	30	-	-	V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250uA	1.1	1.5	1.9	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =30 V _{GS} = 0V	-	-	1.0	uA
Gate- Source Leakage Current	I _{GSS}	V _{GS} =±20V , V _{DS} = 0V	-	-	±100	nA
Static Drain-source On Resistance	R _{DSS(ON)}	V _{GS} =10V, I _D =15A	-	8.5	10	mΩ
		V _{GS} =4.5V, I _D =10A	-	10	13	mΩ
Forward Transconductance	g _{FS}	V _{DS} = 25V, I _D =10A	-	10	-	S
Source-drain voltage	V _{SD}	I _S =10A	-	-	1.20	V

• Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C _{iss}	f = 1MHz V _{DS} =15V V _{GS} =0V	-	927.2	-	pF
Output capacitance	C _{oss}		-	141.1	-	
Reverse transfer capacitance	C _{rss}		-	126.9	-	

• Gate Charge characteristics(T_a = 25°C)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q _g	V _{DD} = 24V ID = 10A V _{GS} = 10V	-	23.0	-	nC
Gate - Source charge	Q _{gs}		-	2.58	-	
Gate - Drain charge	Q _{gd}		-	6.20	-	

Note: ① Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% ;

Typical Electrical and Thermal Characteristics

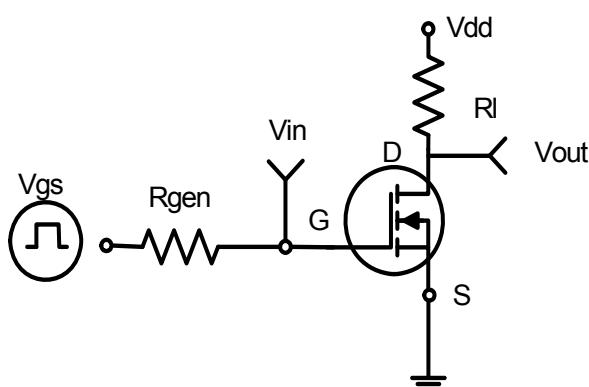


Figure 1 Switching Test Circuit

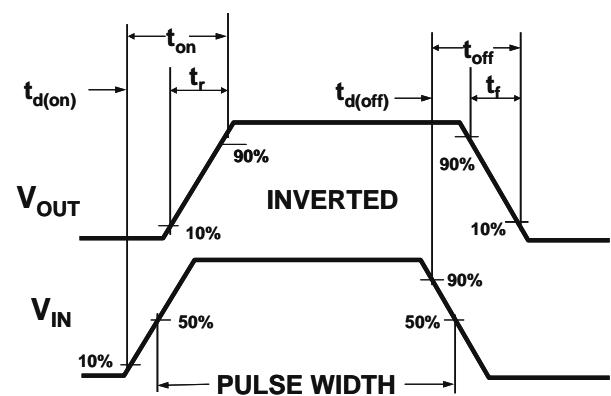
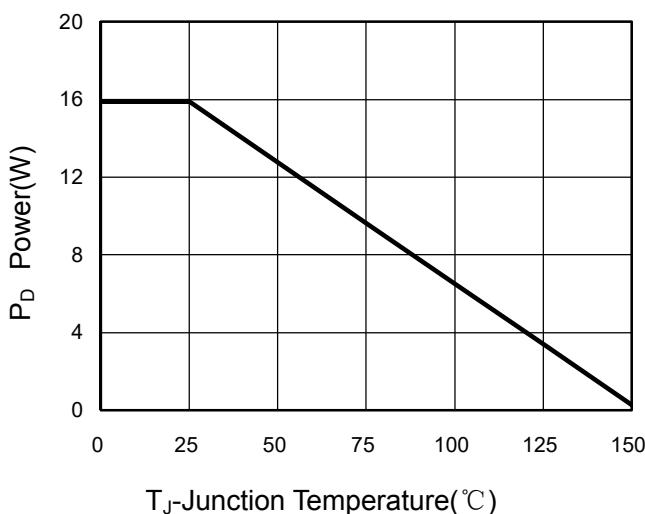
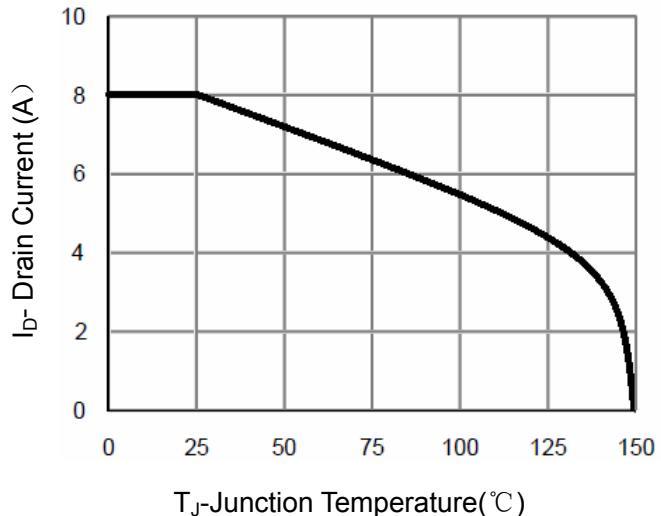


Figure 2 Switching Waveforms



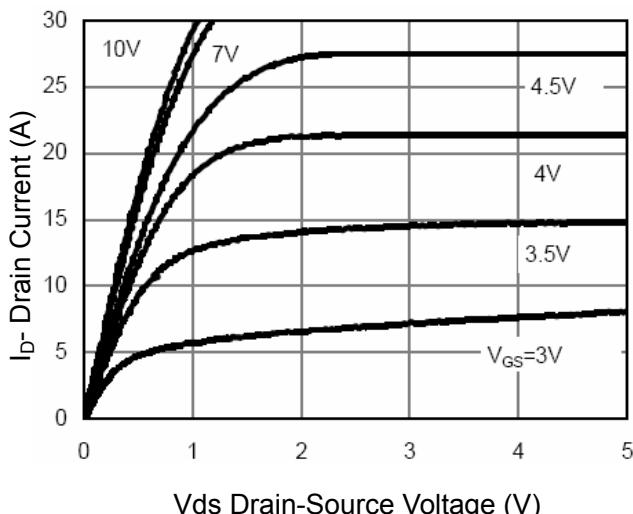
T_J-Junction Temperature(°C)

Figure 3 Power Dissipation



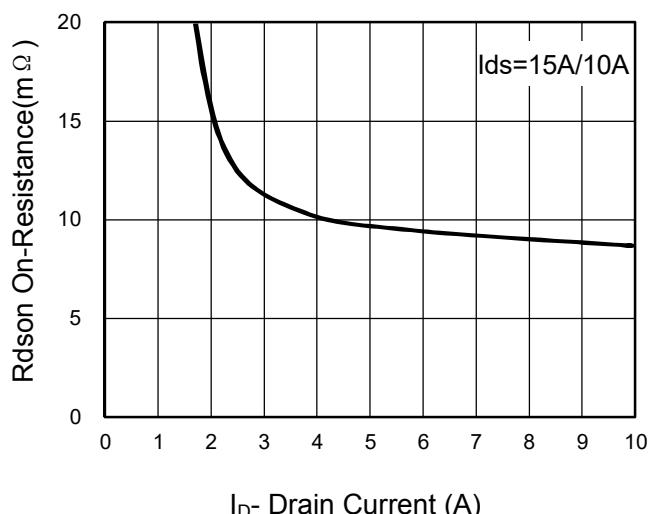
T_J-Junction Temperature(°C)

Figure 4 Drain Current



V_{DS} Drain-Source Voltage (V)

Figure 5 Output Characteristics



I_D- Drain Current (A)

Figure 6 Drain-Source On-Resistance

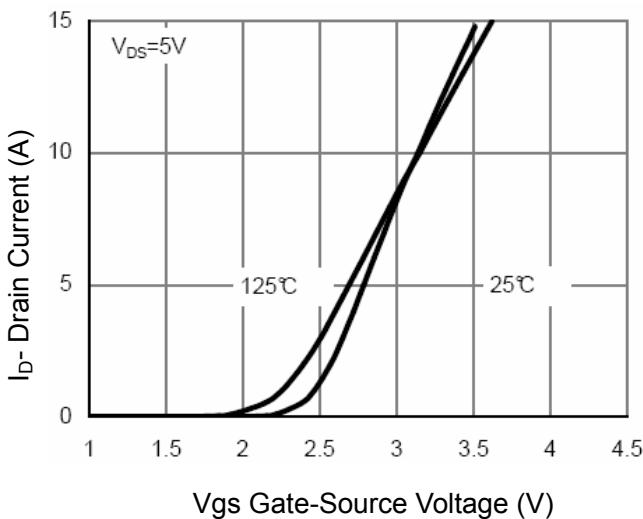


Figure 7 Transfer Characteristics

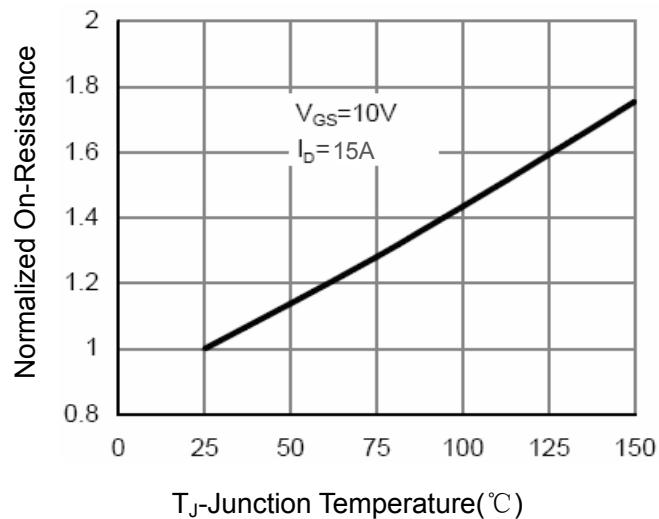


Figure 8 Drain-Source On-Resistance

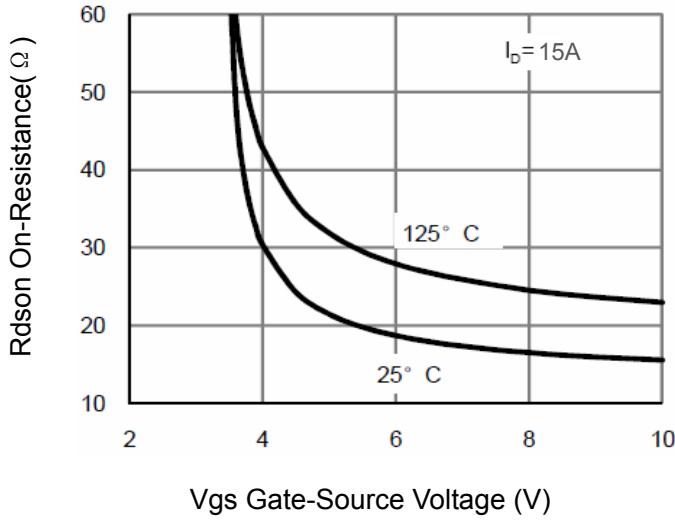


Figure 9 $R_{DS(on)}$ vs V_{GS}

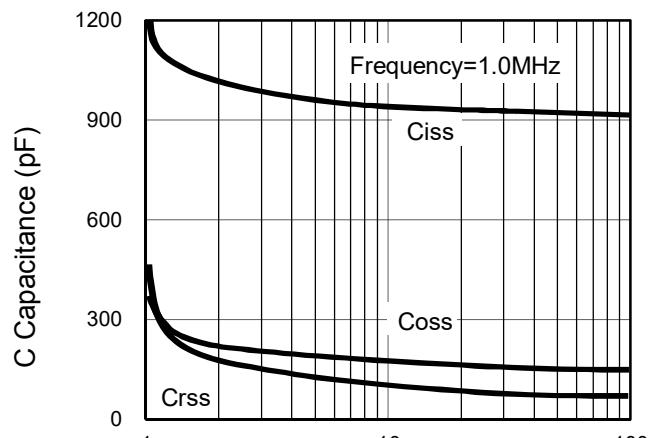


Figure 10 Capacitance vs V_{DS}

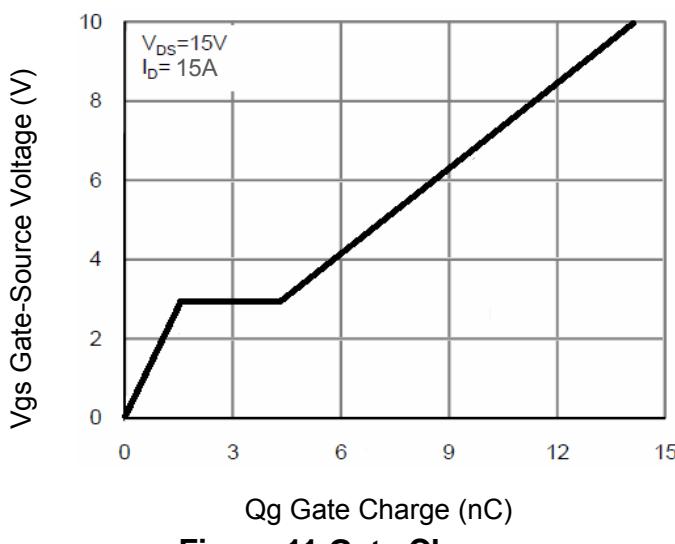


Figure 11 Gate Charge

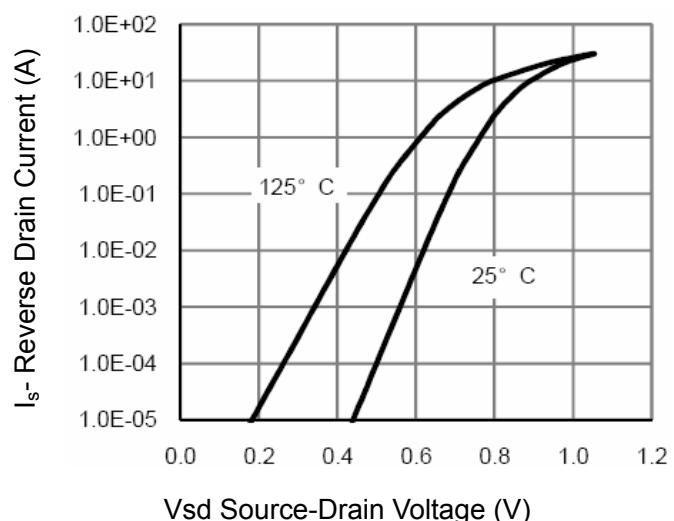


Figure 12 Source- Drain Diode Forward

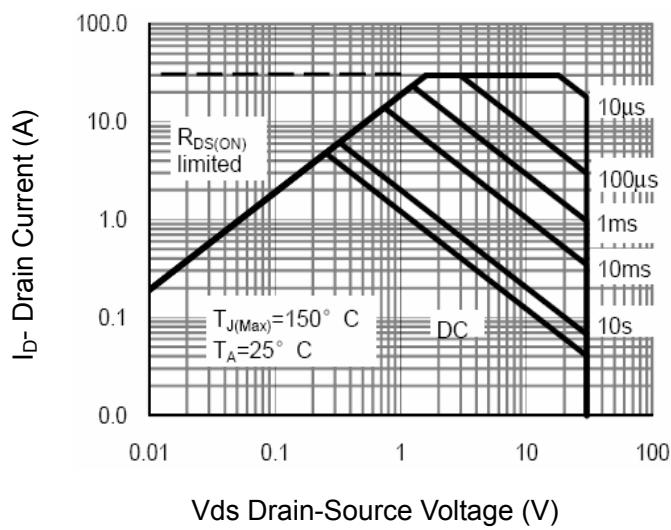


Figure 13 Safe Operation Area

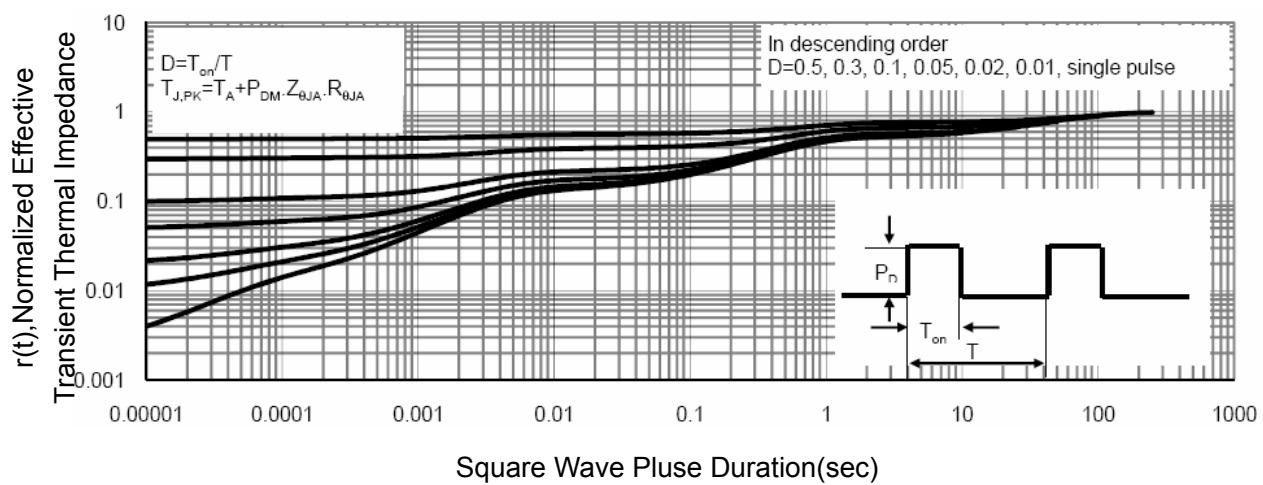
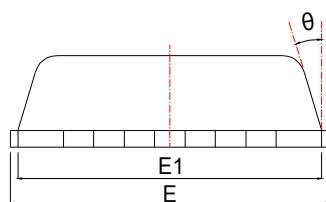
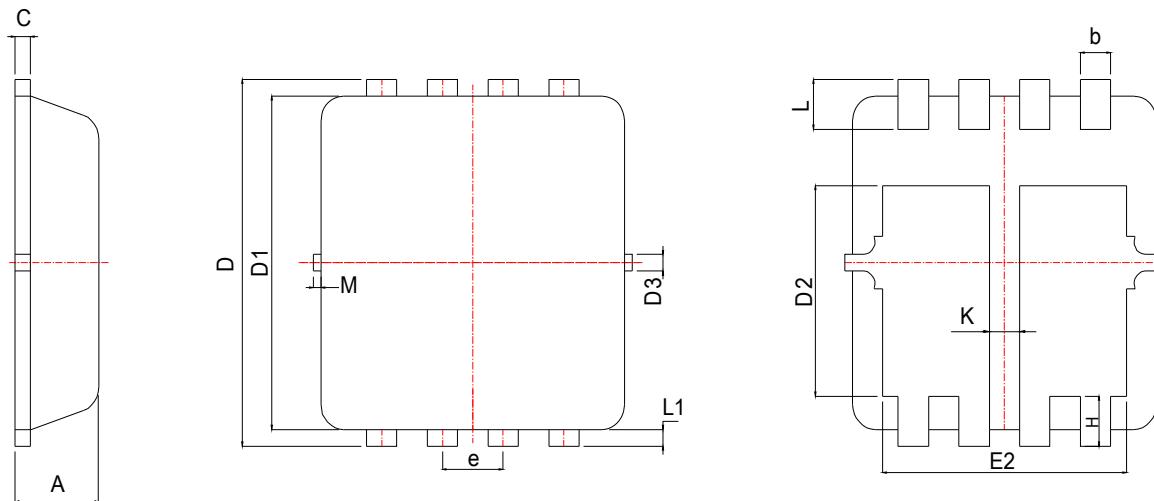
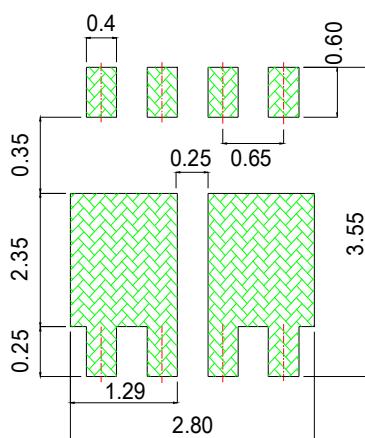


Figure 14 Normalized Maximum Transient Thermal Impedance



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N-CHANNEL ENHANCEMENT MODE POWER MOSFET

TFD085N03M**PDFN3333-8L**Land Pattern
(Only for Reference)

SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX	E1	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0.028	0.030	0.031	E1	3.00	3.15	3.20	0.118	0.122	0.126
b	0.25	0.30	0.35	0.010	0.012	0.014	E2	2.39	2.49	2.59	0.094	0.098	0.102
c	0.10	0.15	0.25	0.004	0.007	0.010	e	0.65BSC			0.026BSC		
D	3.25	3.35	3.45	0.128	0.132	0.136	H	0.30	0.40	0.50	0.012	0.016	0.020
D1	3.00	3.10	3.20	0.118	0.122	0.126	L	0.30	0.40	0.50	0.012	0.016	0.020
D2	1.78	1.88	1.98	0.070	0.074	0.078	L1	*	0.13	*	*	0.005	*
D3	*	0.13	*	*	0.005	*	M	*	*	0.15	*	*	0.006
E	3.20	3.30	3.40	0.126	0.130	0.134	θ	10°	12°	*	10°	12°	
K	0.30	*	*	0.012	*	*							